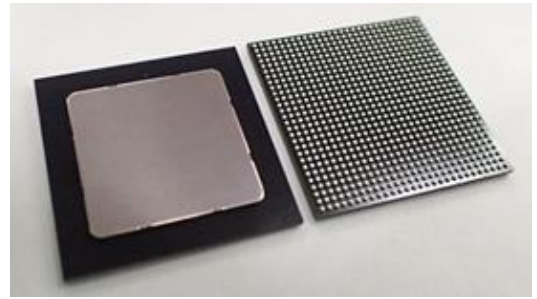


Lidded Flip-Chip Package

Introduction

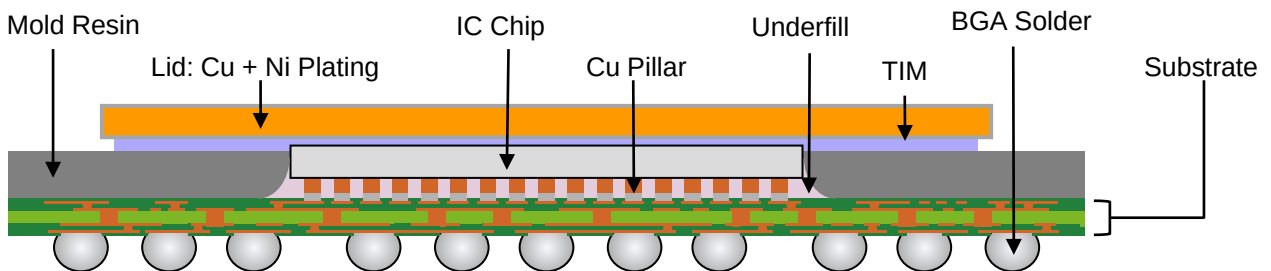
SHINKO provides a high-heat-dissipation flip-chip package that radiates heat to a heat spreader (lid) from the back side of an IC chip through the TIM (Thermal Interface Material).



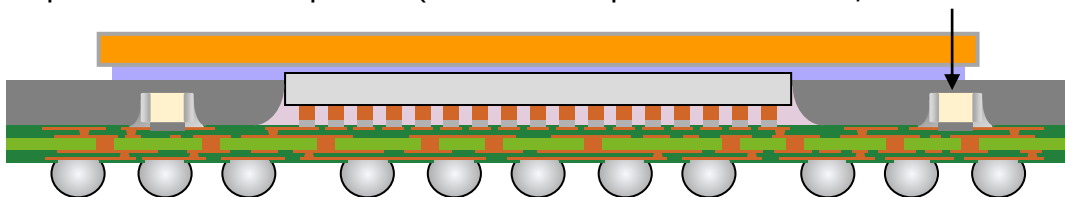
Features

- With the back side of the chip being exposed from the mold resin, the heat generated from the IC chip is dissipated directly to the lid.
- High quality and long-term supply are achieved by adopting an in-house lead-frame as the lid.
- Various types of flip-chip bonding technologies with high density IC chips are available
- A molded exposed die structure under the lid enables low package warpage with a thin substrate.
- Lidded package with thin substrate (such as 200 μm thickness core material) is available.
- Has been applied up to various AEC-Q100 grade 2 capable automotive devices.

Structure



- Option : Built-in component (under development) Capacitor inside mold



Application

- Application processors for car navigation
- Application processors for drones
- Image processors
- IC packages for SSD controllers
- Processors for servers
- LSI packages requiring high-heat dissipation

